



**WANSEMI**  
万芯半导体

**WX065N06D8**

# **Enhancement Mode Single N- Channel Power MOSFET**

SOP8/NMOS/60V/ $\pm 20V$ /1.6V/16.5A/6.5m $\Omega$

Rev0.1

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## 60V, 6.5mΩ, 16.5A, Single N-Channel

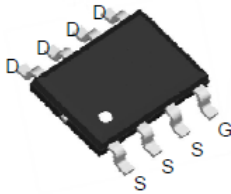
### 1.Features

- ◆ 60V MOSFET technology
- ◆ Low on-state resistance
- ◆ Fast switching
- ◆  $V_{GS} \pm 20V$

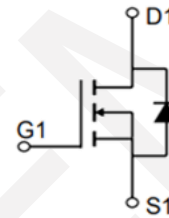
$V_{DS}$	$R_{DS(on)}$ Typ.	$I_D$ Max.
60V	6.5mΩ @ 10V	16.5A
	8.5mΩ @ 4.5V	

### 2.Applications

- ◆ Power Switching Application
- ◆ Load Switching



SOP8  
Pin Description



Schematic Diagram

### 3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WX065N06D8	065N06	SOP8	4,000	48,000

### 4.Absolute Max Ratings at $T_c=25^\circ C$ (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	$V_{DSS}$	60	V
Gate to Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current (DC)	$I_D$	16.5	A
Drain Current (Pulse), $PW \leq 300\mu s$	$I_{DP}$	66	A
Total Dissipation	$P_D$	4.8	W
Avalanche Energy, Single Pulsed	$E_{AS}$	140	mJ
Junction Temperature	$T_j$	150	$^\circ C$
Storage Temperature	$T_{stg}$	-55 to +150	$^\circ C$

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**5. Thermal Resistance Ratings (Note 2)**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	26	$^{\circ}C/W$

Note 2: When mounted on 1 inch square copper board  $t \leq 10$ sec The value in any given application depends on the user's specific board design.

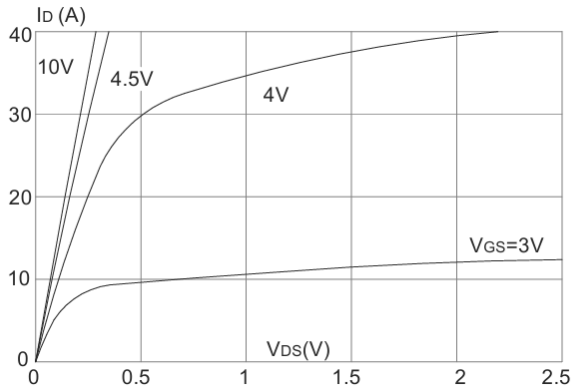
**6. Electrical Characteristics at  $T_a=25^{\circ}C$  (Note 3)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu A, V_{GS} = 0V$	60	-	-	V
Zero-Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 60V, V_{GS} = 0V$	-	-	1.0	$\mu A$
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.3	1.6	2.0	V
Static Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 15A, V_{GS} = 10V$	-	6.5	8.5	m $\Omega$
		$I_D = 10A, V_{GS} = 4.5V$	-	8.5	12	m $\Omega$
Input Capacitance	$C_{iss}$	$V_{GS}=0V,$ $V_{DS}=30V,$ Frequency=1.0MHz	-	1200	-	pF
Output Capacitance	$C_{oss}$		-	550	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	50	-	pF
Turn-ON Delay Time	$t_{d(on)}$		-	9	-	ns
Rise Time	$t_r$	$V_{DS} = 30V, I_D=15A,$ $V_{GS} = 10V, R_G = 1.8\Omega$	-	6.1	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	33.2	-	ns
Fall Time	$t_f$		-	7.5	-	ns
Total Gate Charge	$Q_g$	$V_{DS} = 30V,$ $V_{GS} = 10V,$ $I_D = 10A$	-	98	-	nC
	$Q_{gs}$		-	12.5	-	nC
	$Q_{gd}$		-	32	-	nC
Diode Forward Voltage	$V_{FSD}$	$I_S = 15A, V_{GS} = 0V$	0.5	-	1.2	V

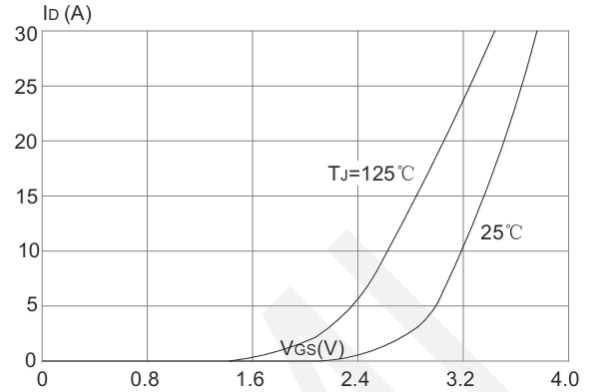
Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



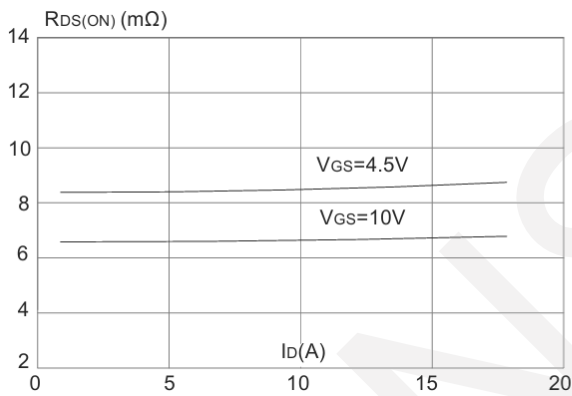
### 7. Typical electrical and thermal characteristics



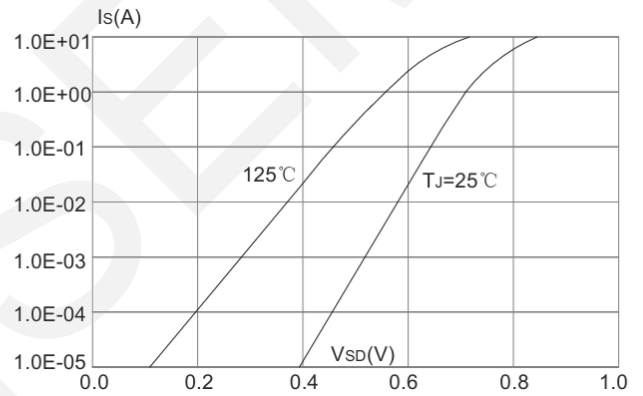
Output Characteristics



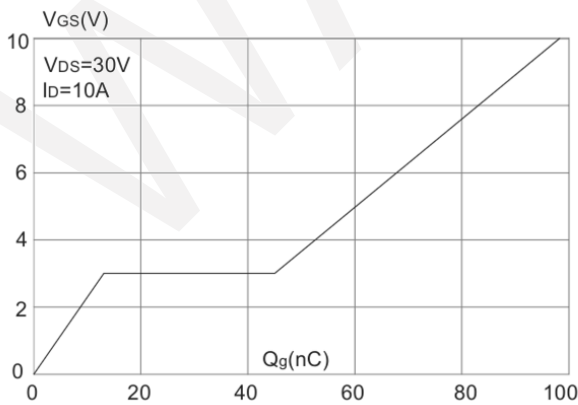
Typical Transfer Characteristics



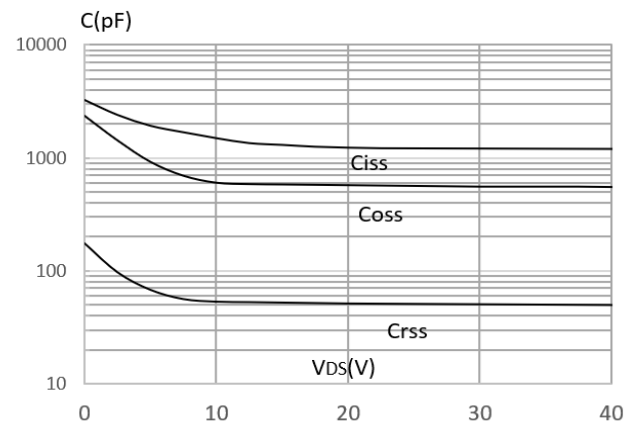
On-resistance vs. Drain Current



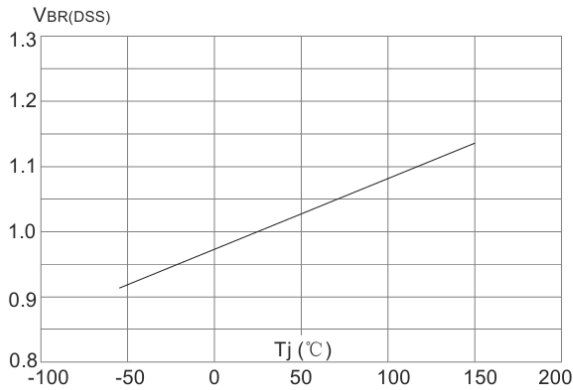
Body Diode Characteristics



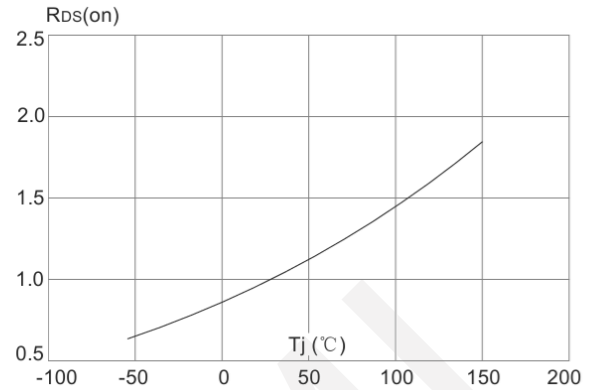
Gate Charge Characteristics



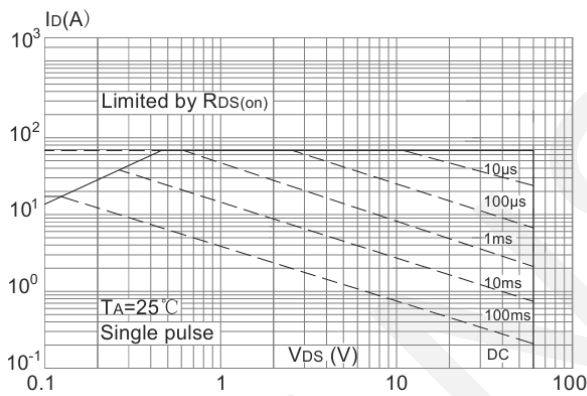
Capacitance Characteristics



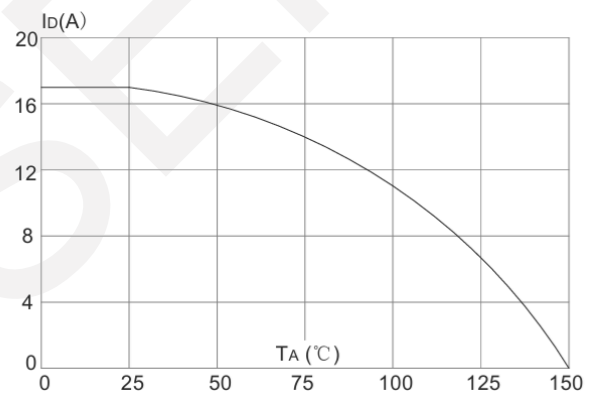
Normalized Breakdown Voltage vs.  
Junction Temperature



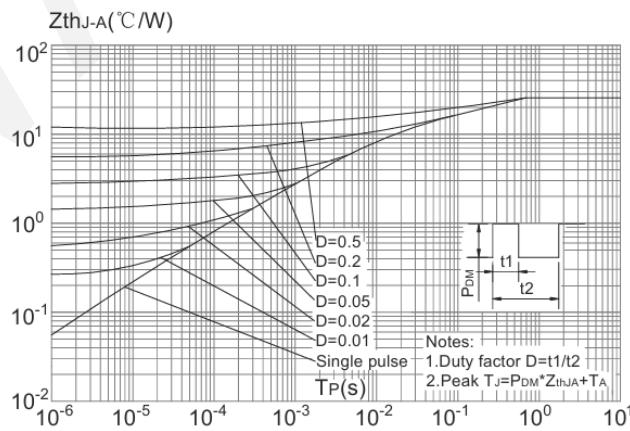
Normalized on Resistance vs.  
Junction Temperature



Maximum Safe Operating Area



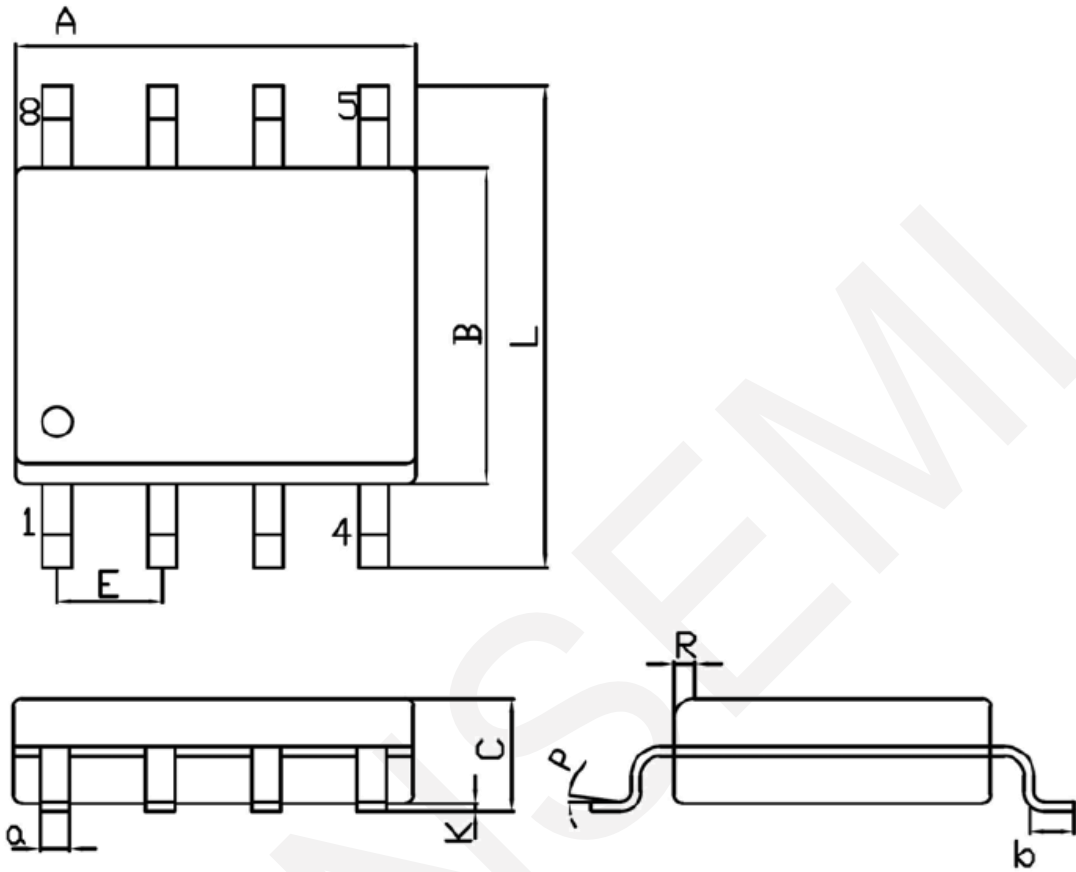
Maximum Continuous Drain Current vs.  
Case Temperature



Normalized Maximum Transient  
Thermal Impedance



**8.Package Dimensions**



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.70	5.10	C	1.35	1.75
B	3.70	4.10	a	0.35	0.49
L	5.80	6.20	R	0.30	0.60
E	1.27BSC		P	0°	7°
K	0.12	0.22	b	0.40	1.25

## 9. Important Notice

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